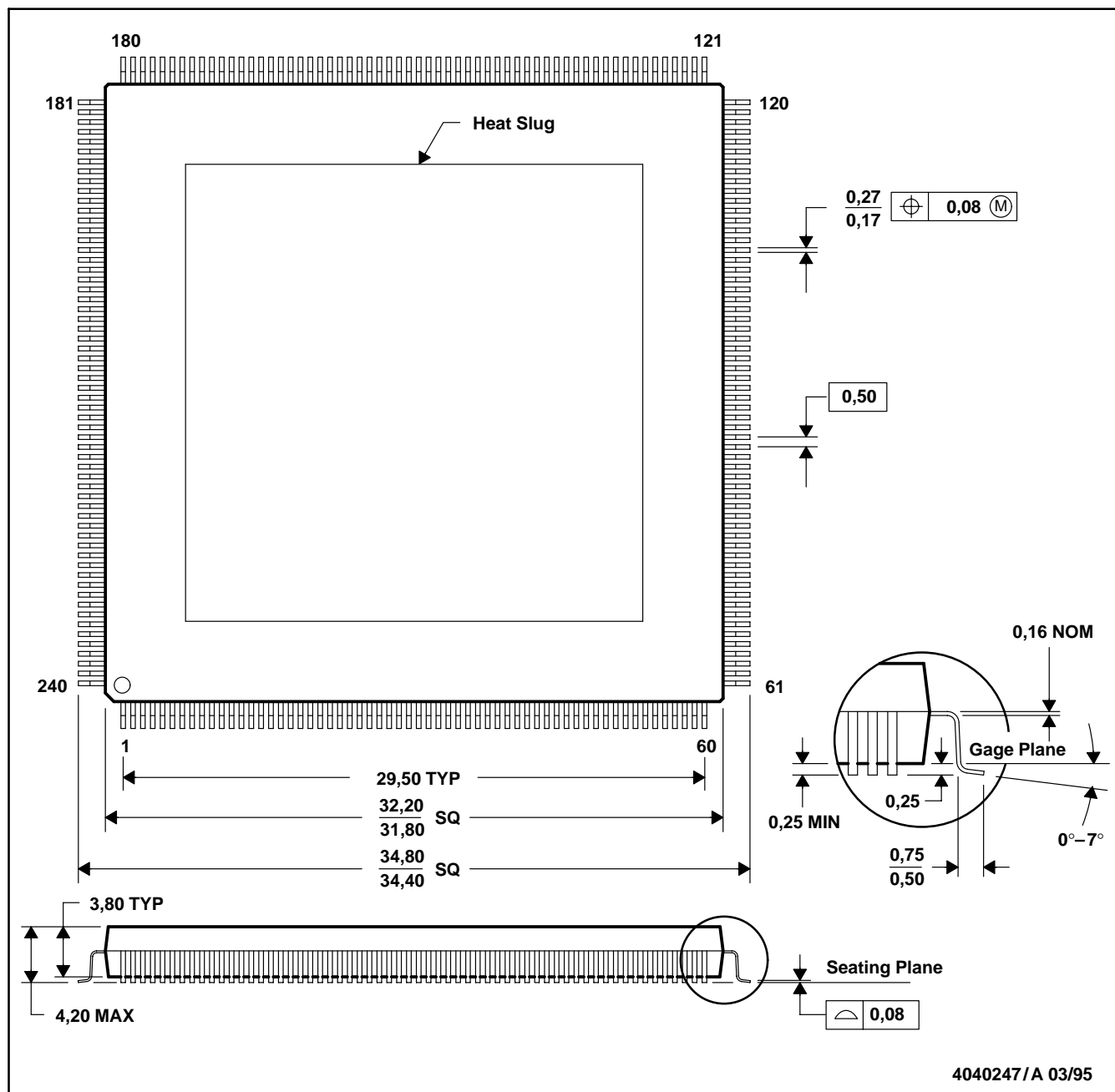


PGV (S-PQFP-G240)

PLASTIC QUAD FLATPACK (DIE-DOWN)



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Thermally enhanced molded plastic package with a heat slug (HSL)

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